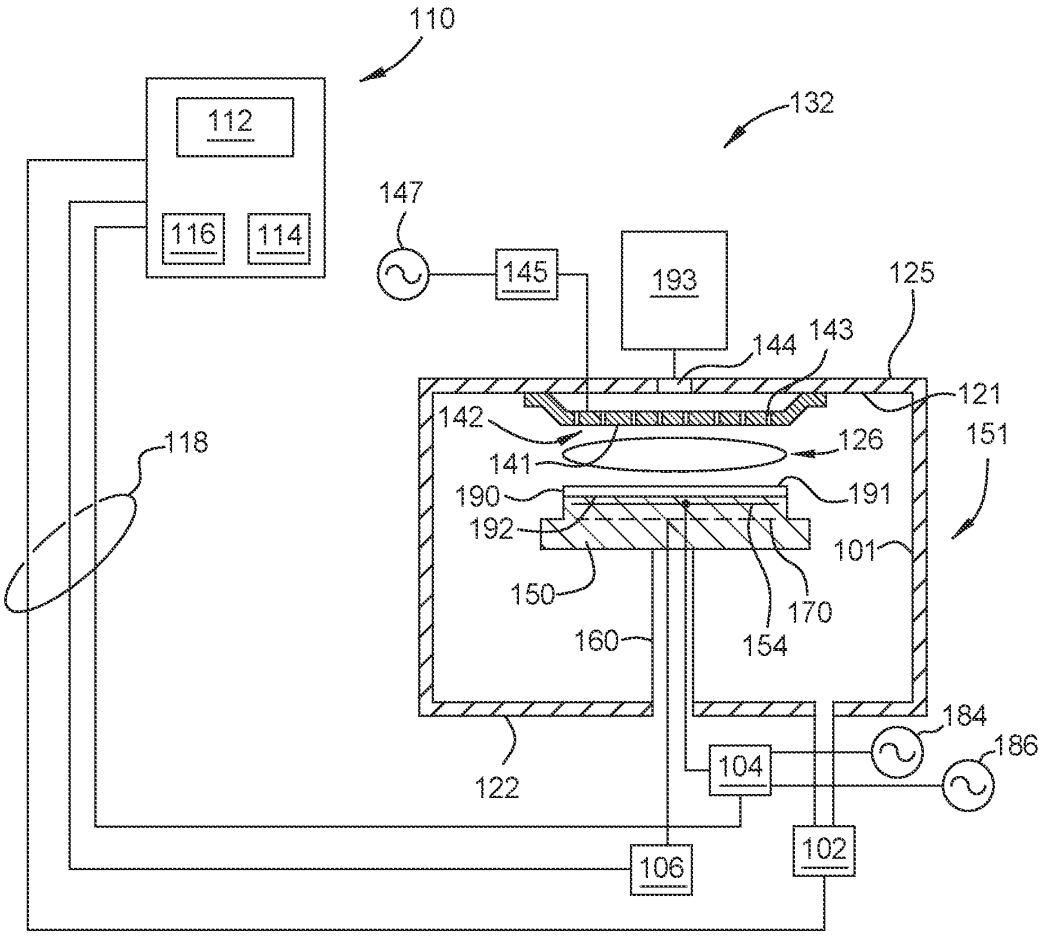

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FIG. 1

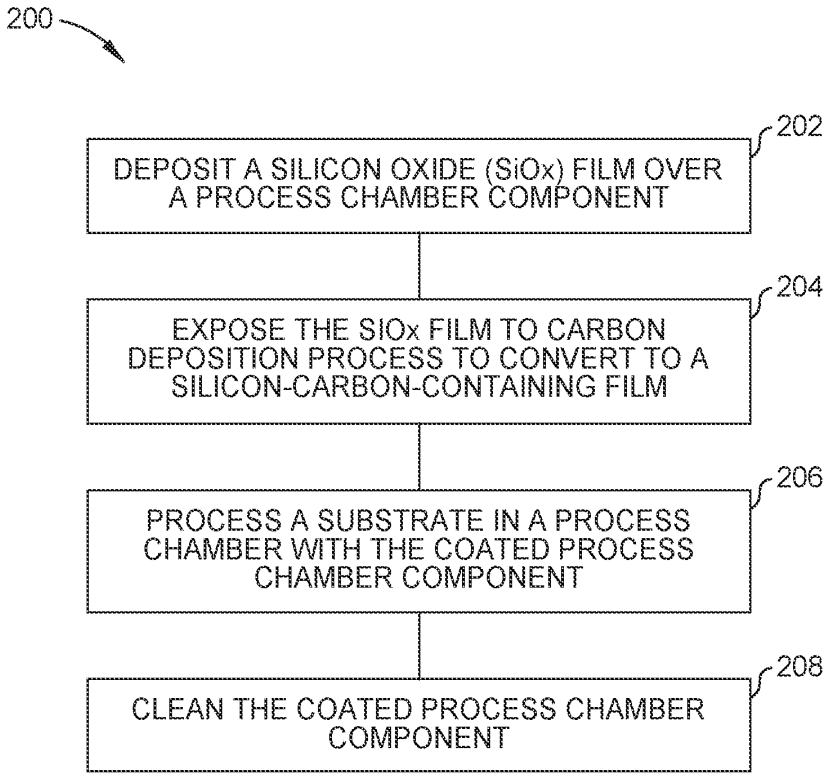

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DEPOSIT A SILICON OXIDE (SiOx) FILM OVER A PROCESS CHAMBER COMPONENT
202
EXPOSE THE SIOx FILM TO CARBON DEPOSITION PROCESS TO CONVERT TO A SILICON-CARBON-CONTAINING FILM
204
PROCESS A SUBSTRATE IN A PROCESS CHAMBER WITH THE COATED PROCESS CHAMBER COMPONENT
206
CLEAN THE COATED PROCESS CHAMBER COMPONENT
208

FIG. 2

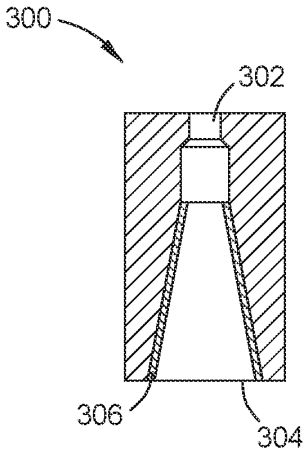

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FIG. 3